

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Original) A paste containing:

solids having a conductive substance and a resin; and

a solvent for dissolving the resin,

wherein a solids content of said paste is not less than 60 vol%.

2. (Original) A paste containing:

solids having a conductive substance and a resin; and

a solvent for dissolving the resin,

wherein a viscosity ratio of said paste is not more than 2.

3. (Original) A paste containing:

solids having a conductive substance and a resin; and

a solvent for dissolving the resin,

wherein a solids content of said paste is not less than 60 vol% and a viscosity ratio thereof is not more than 2.

4. (Canceled)

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5. (Currently amended) A method of burying ~~said a paste defined in claim~~
4 in a trench formed in a major surface of a substrate, comprising:
forming said trench in said substrate; and
burying, in said trench, a paste containing solids having a conductive
substance and a resin, and a solvent for dissolving the resin, wherein a solids
content of said paste is not less than 60 vol%.

6. (Currently amended) A method of burying ~~said a paste defined in claim~~
2 in a trench formed in a major surface of a substrate, comprising:
forming said trench in said substrate; and
burying, in said trench, a paste containing solids having a conductive
substance and a resin; and a solvent for dissolving the resin, wherein a viscosity
ration of said paste is not more than 2.

7. (Currently amended) A method of ~~burying said paste defined in claim 3~~
~~in a trench formed in a major surface of a substrate.~~ according to claim 5,
wherein a viscosity ratio of said paste is not more than 2.

8. (Canceled)

9. (Original) A method of burying powder in a trench formed in a major
surface of a substrate by coating a region including the trench with a solution in
which the powder disperses and precipitating the powder in the solution.

10. (Original) A method according to claim 9, wherein a solution to which a resin is added is used as the solution.

11. (Original) A method according to claim 9, wherein a portion of said powder is a glass powder.

12. (Original) A method according to claim 10, wherein a portion of said powder is a glass powder.

13-24 . (Canceled)

25. (Previously presented) A method according to claim 5, further comprising polishing a lower surface of the substrate to expose the paste buried in said trench.

26. (Previously presented) A method according to claim 5,
wherein said forming the trench includes forming a plug hole in an upper surface of said substrate, and said burying includes burying said paste into said plug hole; and

wherein said method further comprises:

removing the lower surface of the substrate until the paste buried at a bottom portion of said plug hole appears to form a chip-through plug.

27. (Previously presented) A method according to claim 6, further comprising polishing a lower surface of the substrate to expose the paste buried in said trench.

28. (Previously presented) A method according to claim 6, wherein said forming the trench includes forming a plug hole in an upper surface of said substrate, and said burying includes burying said paste into said plug hole, and wherein said method further comprises:

removing the lower surface of the substrate until the paste buried at a bottom portion of said plug hole appears to form a chip-through plug.

29. (Previously presented) A method according to claim 9, further comprising polishing a lower surface of the substrate to expose the powder buried in said trench

30. (Previously presented) A method according to claim 9, wherein said forming the trench includes a plug hole in an upper surface of said substrate, and said burying includes burying said paste into said plug hole; and wherein said method further comprises:

removing the lower surface of the substrate until the powder buried at a bottom portion of said plug hole appears to form a chip-through plug.